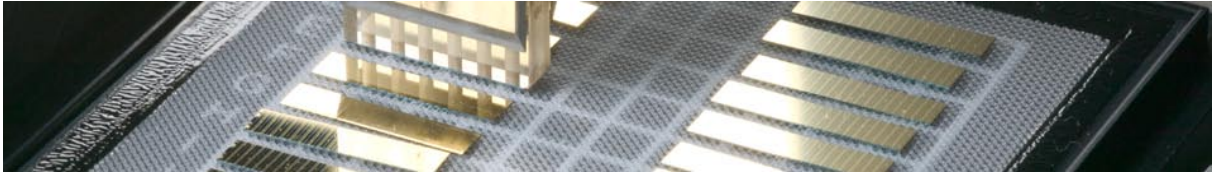


MACHINES

BondLine BL100





BondLine - BL100

The BondLine describes a product family of machines. Especially micro assembly applications such as die bonding and component handling are part of that portfolio.

The BL100 from ficonTEC is a versatile handling platform equipped with a beam splitter and a programmable z-axis. The BL100 has especially been designed for micro assembly applications like die bonding, sorting or assembling to be performed on a table top system.



Best Solutions for Best Practice

The BL100 is a versatile handling system designed for micro assembly applications like die bonding and component handling. The BL100 is an assembling platform in an overhead gantry arrangement with an integrated beam splitter. This arrangement provides a maximum working area at minimal installation area. With the integrated beam splitter in combination with the programmable z-axis this system is well suited for simple sorting or assembly applications as well as for reproducible bonding of electronic and opto-electronic components. Available options to support the bonding process are heating plates, heated placement heads or dispenser.

Applications

- + component sorting
- + die bonding
- + flip chip bonding / assembly
- + MEMS / MOEMS assembly
- + sensor assembly
- + assembly of optical components
(photo diodes, laser diodes)
- + assembly of mechanical components
- + applications in the field of medical technology

Technical Specifications

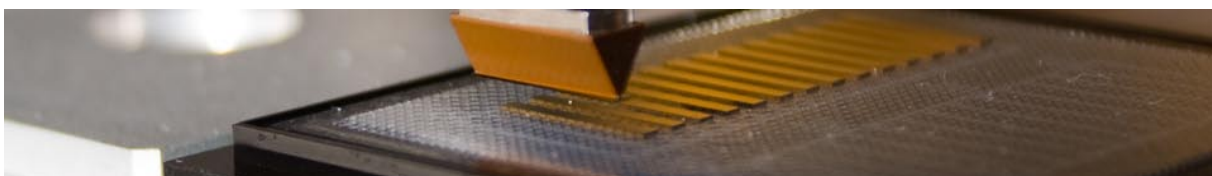
- + beam splitter
- + zoom camera with 27-x optical zoom
- + programmable z-axis
- + force range: 0,2 - 200 N
- + placement accuracy: ± 5 micron
- + adjustment screws for x- and y-axis
- + component size (max.):
50 mm x 50 mm (2" x 2")
- + working area:
300 mm x 300 mm x 50 mm (12" x 12" x 2")

Options

- + dispenser module
- + heating plates
- + heated placement heads
- + support plate with vacuum
- + inspection camera

Technologies

- + thermo-compression bonding
(eutectic, Au/Au, Au/Sn bonding)
- + adhesive bonding
- + dispensing
- + stamping





Contact us worldwide

EUROPE

ficonTEC Service GmbH (Headquarter) • Desmastraße 3-5 • 28832 Achim • Germany
Phone: +49 (0)4202 51160-0 • Fax: +49 (0)4202 51160-90 • info@ficontec.com

USA

ficonTEC (USA) Corporation • 25 Calle Canela • San Clemente, CA 92673 • USA
Phone: +1 949 388-5800 • Fax: +1 949 388-1489 • usa@ficontec.com

ASIA

ficonTEC Service GmbH Shanghai Rep. Office • Rm. 1038, Central Plaza
No. 381 Huai Hai Zhong Road • Shanghai 200021 • China
Phone: +86 (0)21 52730985 • Fax: +86 (0)21 52730985 • china@ficontec.com

ficontec.com